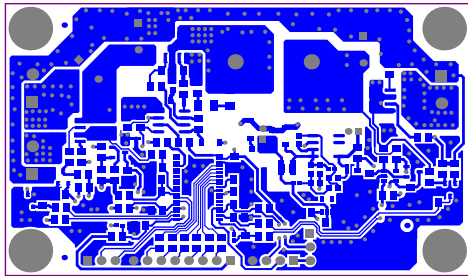
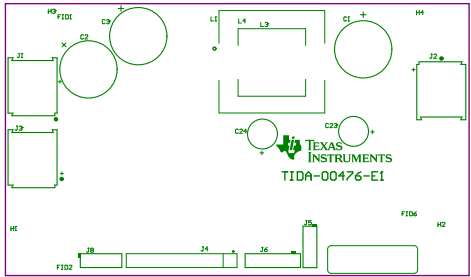


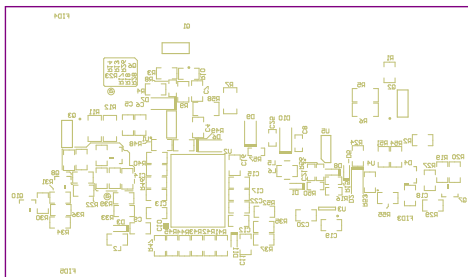
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00476 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME= Top Layer | | | |
| PLOT NAME=Top Layer | GENERATED : 9/24/2015 1:28:16 PM | TEXAS INSTRUMENTS | |



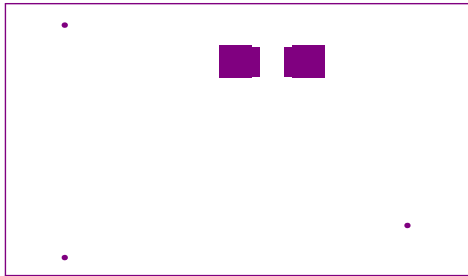
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00476 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME= Bottom Layer | | | |
| PLOT NAME=Bottom Layer | GENERATED : 9/24/2015 1:28:16 PM | TEXAS INSTRUMENTS | |



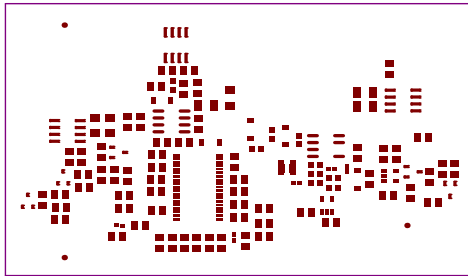
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00476 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME= Top Overlay | | | |
| PLOT NAME=Top Silkscreen Overlay | GENERATED : 9/24/2015 1:28:16 PM | TEXAS INSTRUMENTS | |



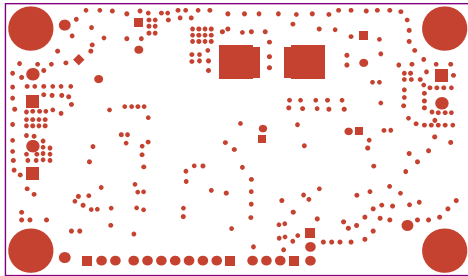
| | | | |
|-------------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00476 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME= Bottom Overlay | | | |
| PLOT NAME=Bottom Silkscreen Overlay | GENERATED : 9/24/2015 1:28:16 PM | TEXAS INSTRUMENTS | |



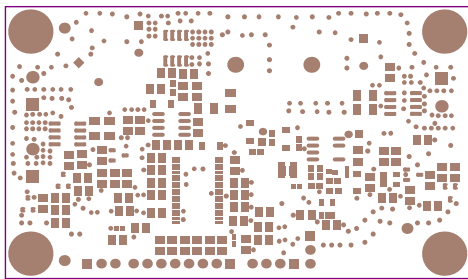
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00476 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME= Top Paste | | | |
| PLOT NAME=Top Paste Mask Print | GENERATED : 9/24/2015 1:28:16 PM | TEXAS INSTRUMENTS | |



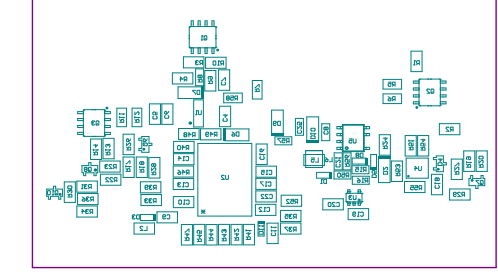
| | | | |
|-----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00476 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME= Bottom Paste | | | |
| PLOT NAME=Bottom Paste Mask Print | GENERATED : 9/24/2015 1:28:17 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00476 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME= Top Solder | | | |
| PLOT NAME=Top Solder Mask Print | GENERATED : 9/24/2015 1:28:17 PM | TEXAS INSTRUMENTS | |



| | | | |
|------------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00476 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME= Bottom Solder | | | |
| PLOT NAME=Bottom Solder Mask Print | GENERATED : 9/24/2015 1:28:17 PM | TEXAS INSTRUMENTS | |

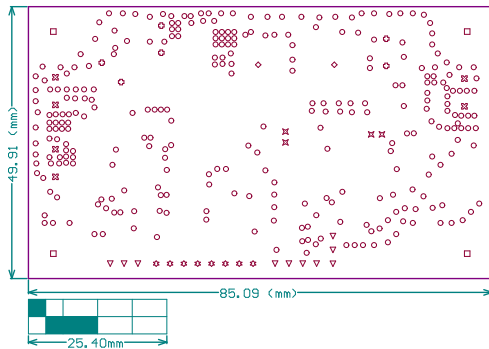


| | | | |
|--------------------------------|----------------------------------|-------------------|--------------------------------|
| PCB VIEWED FROM BOTTOM SIDE | BOARD #: TIDA-00426 | REV: E1 | SUN REV: Not In VersionControl |
| | LAYER NAME = M6 Assembly Bottom | | |
| PLOT NAME = M6 Assembly Bottom | GENERATED : 2-24-2018 1:28:17 PM | TEXAS INSTRUMENTS | |

COMPONENTS MARKED 'DNP', SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT (No Variants)

| Symbol | Hit Count | Tool Size | Plated | Hole Type |
|--------|-----------|--------------------|--------|-----------|
| ○ | 292 | 0.457mm (18mil) | PTH | Round |
| ⊗ | 4 | 0.75mm (29.528mil) | PTH | Round |
| ⊙ | 6 | 0.85mm (33.465mil) | PTH | Round |
| ▽ | 10 | 1mm (39.37mil) | PTH | Round |
| ⊛ | 8 | 1.016mm (40mil) | PTH | Round |
| ⊗ | 6 | 1.4mm (55.118mil) | PTH | Round |
| ◇ | 2 | 1.702mm (67mil) | PTH | Round |
| □ | 4 | 3.2mm (125.984mil) | PTH | Round |
| | 332 Total | | | |

Drill Table
 DRILL TOLERANCE
 FOR PTH +/- 3MIL
 18mil drill:+0/-18mil



Layer Stack Up Detail for: TIDA-00476-E1.PcbDoc

| Layer Name | Order Designator | Copper Thickness | Dielectric Height | Dielectric Material | Dielectric Constant | Dielectric Type |
|--------------------|------------------|------------------|-------------------|---------------------|---------------------|-----------------|
| Top Solder Mask | (.GTS) | | 0.4mil | Solder Resist | 3.90 | |
| Top Layer | (.OTL) | 1.4mil | 58.2mil | FR-4 High Tg | 4.80 | Core |
| Bottom Layer | (.OBL) | 1.4mil | | | | |
| Bottom Solder Mask | (.GBS) | | 0.4mil | Solder Resist | 3.90 | |

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
 85.09MM X 49.91MM

Number of Layers : 2
 MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 7.824MIL
 MIN. VIA PAD SIZE: 34 MIL

MINIMUM ANNULAR RING 0.203mm (8MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- .5 MIL, HOLES +/- .3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER

THICKNESS: 63 MIL (1.6mm) +/-10% OTHER

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/-

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/-

COPPER THICKNESS (FINISHED):
 OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES

PTH MIN COPPER THICKNESS: 1MIL OTHER

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER

SOLDER RESIST COLOR:
 GREEN BLUE OTHER

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPG
 IMM. TIN/SILVER OR EQUIV OTHER

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS: VIA TENTING YES NO
 MICROSECTION: YES IMPEDANCE CONTROL: YES NO X
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S UL: RAL METAL SILK



PROJECT TITLE:
TIDA-00476_CARD

DESIGNED FOR:
Public Release

FILE NAME:
TIDA-00476_E1.PcbDoc

| | | | | | | |
|--|----------------------------------|-------------------|---------------------------------|--|---|------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-00476 | REV: E1 | SUN REV: Not In Version Control | Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application. | ENGINEER: Saili Chellappan | LAYOUT BY: Manjunatha T N |
| LAYER NAME= Drill Drawing | GENERATED : 9/24/2015 1:28:18 PM | TEXAS INSTRUMENTS | | | ALTIUM DESIGNER VERSION: 14.3.14.34663 | |
| PLOT NAME=Drill Drawing For (Bottom Layer, Top | | | SCALE: 0.72 | | | |

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